

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): S. Tsuchikawa, et al.  
Application No.: TBD  
Filed: October 31, 2003  
For: THERMOSETTING RESIN COMPOSITION AND USE THEREOF  
Expected  
Group: 1712  
Expected  
Examiner: D. Aylward

**PRELIMINARY AMENDMENT**

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

October 31, 2003

Sir:

Please amend the above-identified application, prior to examination thereof,  
as listed in the following, and as set forth on the following pages:

Amendments to the Specification; and

Remarks are included following the amendments.